April 17 (Wed.)

9:50 — **OPENING CEREMONY**

10:00 – 12:40

WA1: High Speed / High Frequency Packaging

Chairperson: R. Tummala (Georgia Institute of Technology)
O. Ibaragi (ASET)

1. **Directions in Rf Module Packaging (Session Invite)**
   S.-K. Chiang, Prismark Partners / U.S.A.
2. The High Frequency Package Using an Organic Material
   T. Fujii, Shinko Electric Industries / Japan
3. The New Organic Laminate for Over GHz Packaging
   T. Seri, Kyocera / Japan
4. Development of High Pin Count FCBGA(LTCC) for High Speed(2.5GBps) ASIC Application
   A. Kikuchi, Fujitsu / Japan
5. The Study of RF Characteristics for QFP/BGA Applications
   C.-M. Ko, ASE TEST, Y.-J. Huang, S.-L. Fu, I-Shou University / Taiwan
6. Evaluation of Propagation Characteristics in High-speed Differential Signal Pair
   J. Kudo, T. Sudo, Toshiba / Japan
7. Characteristic Impedance Control of Multilayer PWB in Dual Stripline Structure
   I. Kaneda, Oki Printed Circuits / Japan
8. The Spiral Inductor Design Consideration in Wafer Scale Package
   C. Azuma, Texas Instruments, Japan / Japan

WB1: Pb-free Solders

Chairperson: M. Otsuka (Shibaura Institute of Technology)
H. Sawai (Oki Electric Industry)

1. **JIEP Low Temperature Soldering Project (Session Invite)**
   K. Suganuma, Osaka University / Japan
2. An Assessment of Lead-free Soldering for Automotive Applications : Influence of the Components Finishes on the Reliability of Solder Joints
   A. Guedon, E. Woirgard, C. Zardini, Universite Bordeaux 1 / France
3. Comparison of Fractures by Mechanical Stress Test and Degradation by Thermal Stress Test in Lead-free Solders
   Y. Takenaka, Omron / Japan
4. Joining Reliability of Sn-Ag-Cu Series Solder Alloys
   K. Kim, Osaka University / Japan
5. Mechanical Characterization of Sn-Ag-Based Lead Free Solders
   M. Amagai, M. Watanabe, Texas Instruments, Japan,
   M. Omiya, K. Kishimoto, Tokyo Institute of Technology / Japan
6. A New Bumping Process Using Non-residue and Lead-free Solder Paste
   K. Saito ,T. Itoh, T. Suga, University of Tokyo / Japan
7. Development of Thermodynamic Tool for Micro-soldering Alloy
   X. J. Liu, I. Ohnuma, R. Kainuma, H. Ohtani, K. Ishida, Tohoku University / Japan
8. Segregation in Pb-free Solder Joints of Surface Mount Packages Caused by Wave-soldering Process
   T. Nakatsuka, Hitachi / Japan

LUNCH TIME

13:40 – 14:10

Invited Speech

Chairperson: S. Denda (Nagano Prefectural Institute of Technology)
K. Hashimoto (Fujitsu Laboratories)

Device Packaging in the Year 2020
Dr. C. E. Bauer, TechLead Corporation / U.S.A.

14:10 – 16:40

Asia Session

Chairperson: S. Denda (Nagano Prefectural Institute of Technology)
K. Hashimoto (Fujitsu Laboratories)

1. Development of Microelectronic Packaging Technology in Tsinghua University
   Prof. J. Ma, Technology in Tsinghua University / China
2. Introduction to Electronic Packaging Activities in Hong Kong
   Prof. J.-K. Kim, Hong Kong University of Science & Technology / Hong Kong
3. Recent Packaging Technology Development Korea
   Dr. Y.-B. Sun, Kyonggi University / Korea
4. Electronics, Optics & MEMS: Component and Microsystems Packaging in Singapore - Technology Roadmap , Research Collaborations & Relevance to Industry
   Dr. M. K. Iyer, Institute of Microelectronics / Singapore
5. Taiwan Packaging Status
   Dr. S.-L. Fu, I-Shou University / Taiwan

16:40 – 16:55 — **AWARDING CEREMONY**

18:00 – 20:00 — **WELCOME RECEPTION**

The Harbor Circus
Dai-ichi Hotel Tokyo Seafort, 3F.